

AMENDMENTS TO THE SPECIFICATION

On page 9, please replace the last paragraph beginning on line 12, which extends to page 10, with the following:

Figure 7 is a cross-sectional illustration of a second exemplary embodiment of a semiconductor assembly 300 with second and third semiconductor dies 30, 45 secured to a first semiconductor die 20 using the techniques described above. As shown in Figure 7, when the adhesive fillet 24_b is eliminated, there can be cavities 25 between each of the second and third semiconductor dies 30, 45 and between the first semiconductor die 20 and the supporting structure 10. It is to be understood that the elimination of the adhesive fillet 24_b as discussed in Figure 1 covers a wide range of semiconductor configurations involving multiple dies with various sizes, dimensions, and electrical contact techniques. The above described invention has the advantage of allowing either the size of the second and third semiconductor dies 30, 45 to be increased or allowing the size of the first semiconductor die 20 to be reduced by eliminating the wasted space occupied by the adhesive fillet 24.

BEST AVAILABLE COPY